



Description

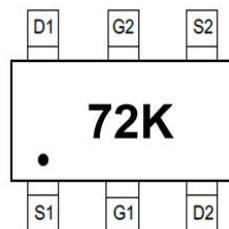
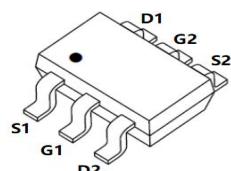
JMT N-channel MOSFET

Features

- $V_{DS}=60V$, $I_D=0.2A$
- $R_{DS(ON)}<2.1\Omega$ @ $V_{GS} = 10V$
- $R_{DS(ON)}<2.7\Omega$ @ $V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired
- ESD Protected: 2KV

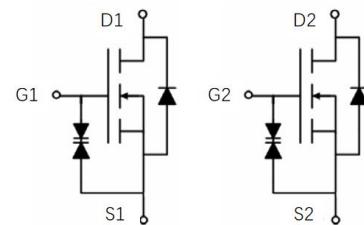
Application

- Battery Operated Systems
- Direct logic-level Interface: TTL/CMOS
- Solid-State Relays



SOT-363 top view

Marking and pin Assignment



Schematic diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
72K	JMTLB2N7002KDS	TAPING	SOT-363	7inch	3000	180000

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		60	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ C$	0.2	A
		$T_A = 100^\circ C$	0.13	
I_{DM}	Pulsed Drain Current ^{note1}		0.8	A
P_D	Power Dissipation	$T_A = 25^\circ C$	0.14	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		893	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

**Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D = 10\mu\text{A}$	60	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 60\text{V}$, $V_{GS} = 0\text{V}$,	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS} = 0\text{V}$, $V_{GS} = \pm 20\text{V}$	-	-	± 10	μA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	1	-	2.5	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS} = 10\text{V}$, $I_D = 0.3\text{A}$	-	1.6	2.1	Ω
		$V_{GS} = 4.5\text{V}$, $I_D = 0.2\text{A}$	-	1.9	2.7	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$, $f = 1.0\text{MHz}$	-	28	-	pF
C_{oss}	Output Capacitance		-	11	-	pF
C_{rss}	Reverse Transfer Capacitance		-	4	-	pF
Q_g	Total Gate Charge	$V_{DS} = 10\text{V}$, $I_D = 0.3\text{A}$, $V_{GS} = 4.5\text{V}$	-	1.7	-	nC
Q_{gs}	Gate-Source Charge		-	0.3	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	0.6	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 30\text{V}$, $I_D = 0.2\text{A}$, $R_{\text{GEN}} = 10\Omega$, $V_{GS} = 10\text{V}$	-	10	-	ns
t_r	Turn-on Rise Time		-	50	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	17	-	ns
t_f	Turn-off Fall Time		-	10	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	0.2	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	0.8	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}$, $I_s = 0.2\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

Typical Performance Characteristics

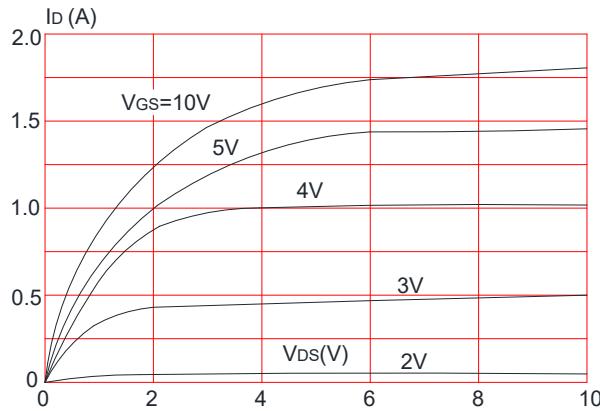
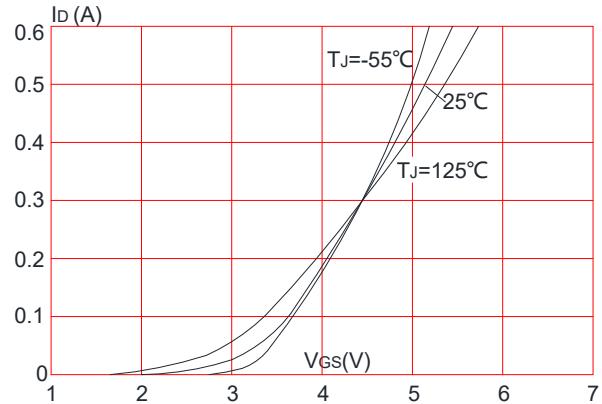
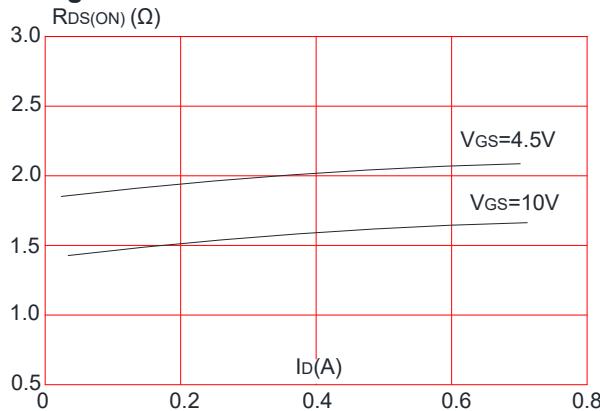
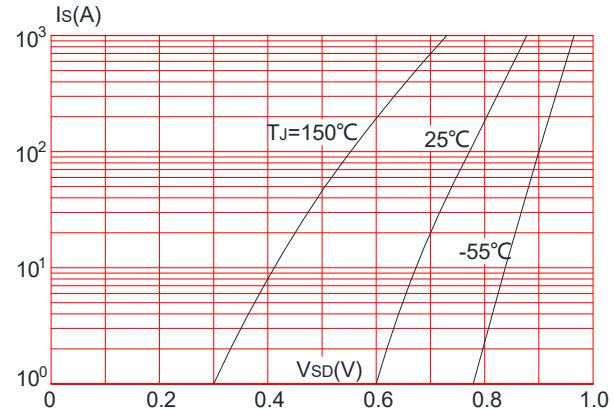
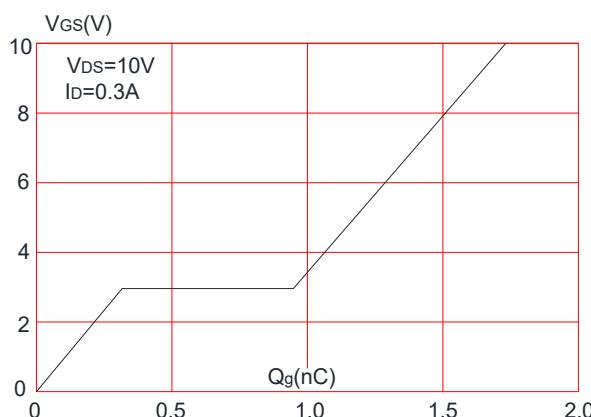
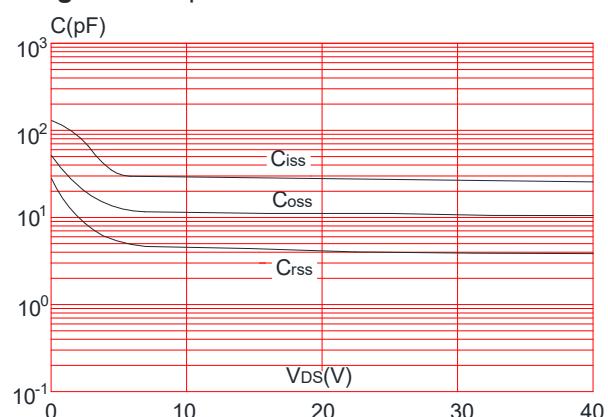
Figure1: Output Characteristics**Figure 2:** Typical Transfer Characteristics**Figure 3:** On-resistance vs. Drain Current**Figure 4:** Body Diode Characteristics**Figure 5:** Gate Charge Characteristics**Figure 6:** Capacitance Characteristics

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

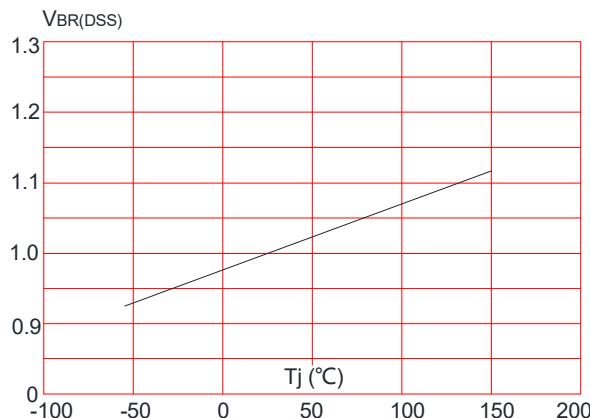


Figure 9: Maximum Safe Operating Area

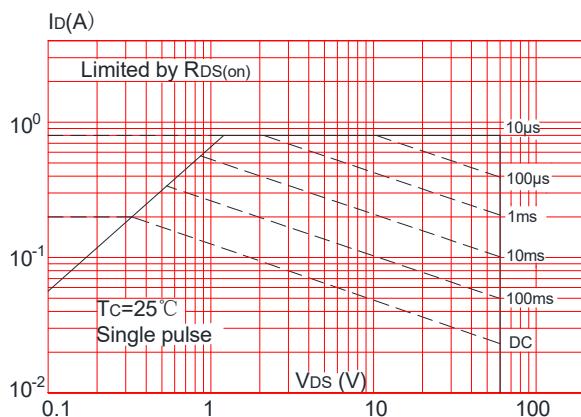


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

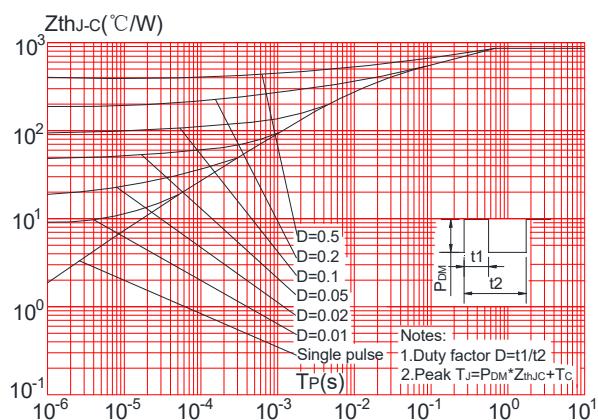


Figure 8: Normalized on Resistance vs. Junction Temperature

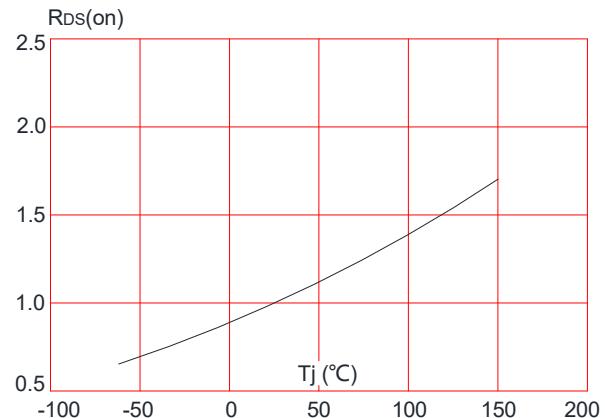
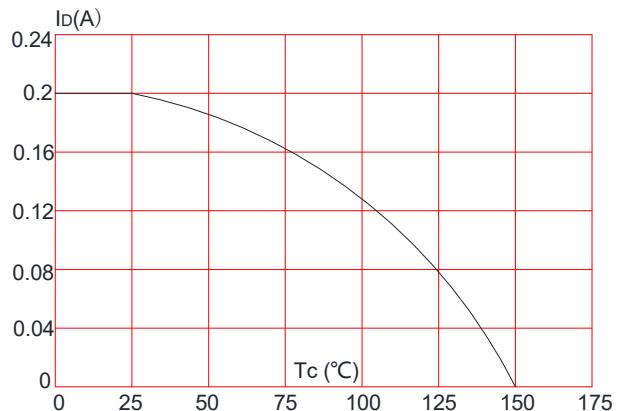


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



Test Circuit

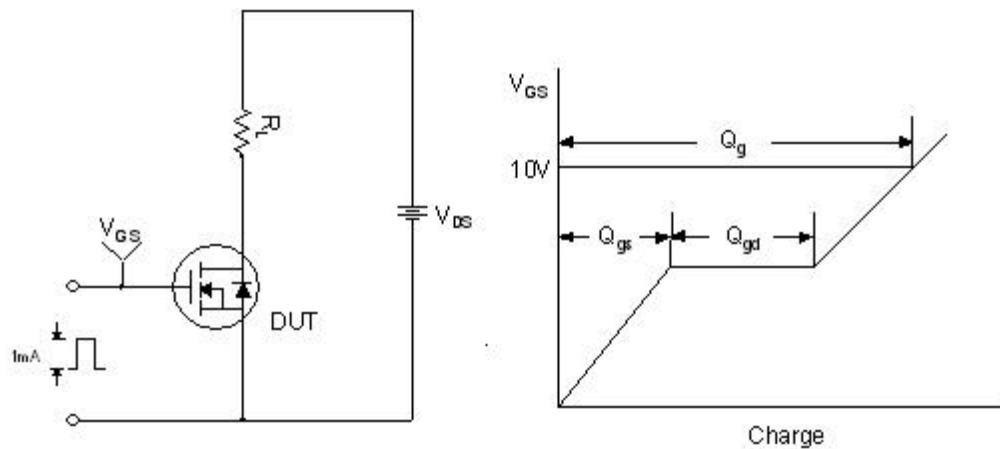


Figure 1. Gate Charge Test Circuit & Waveform

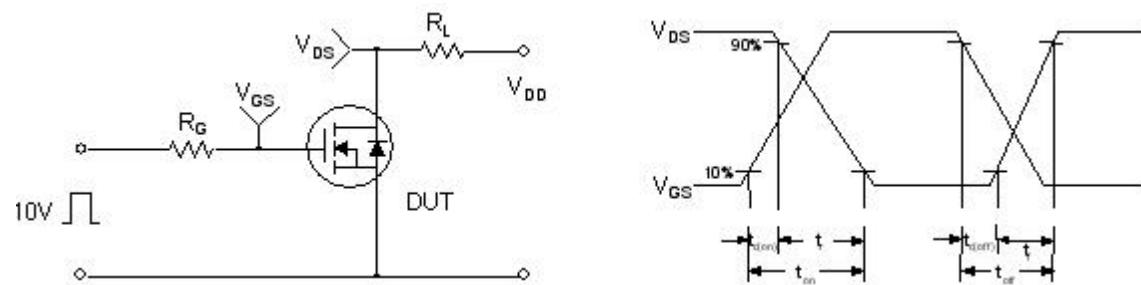


Figure 2. Resistive Switching Test Circuit & Waveforms

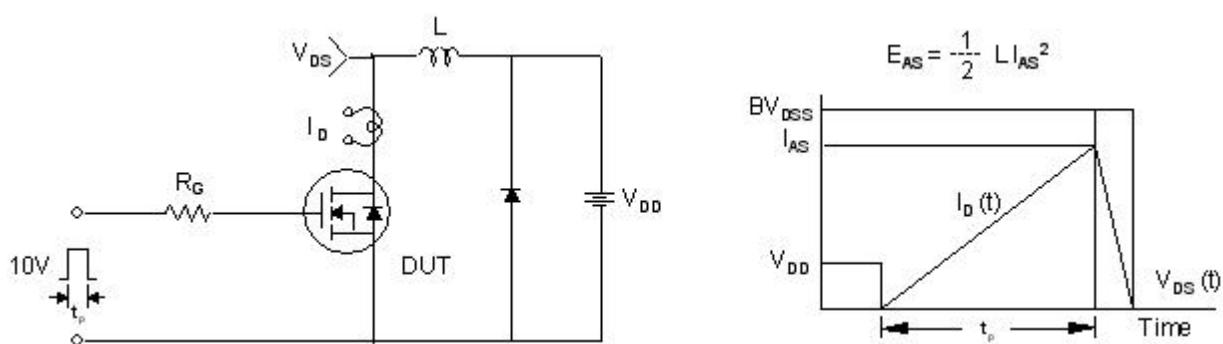
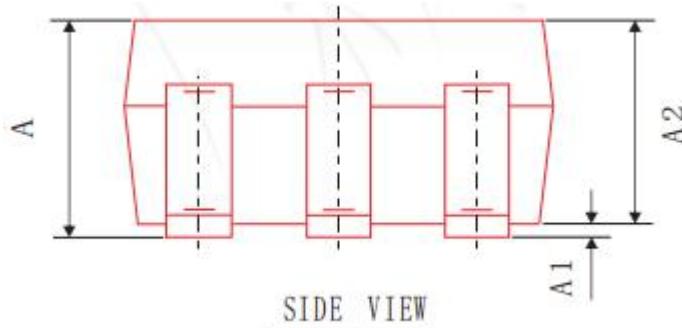
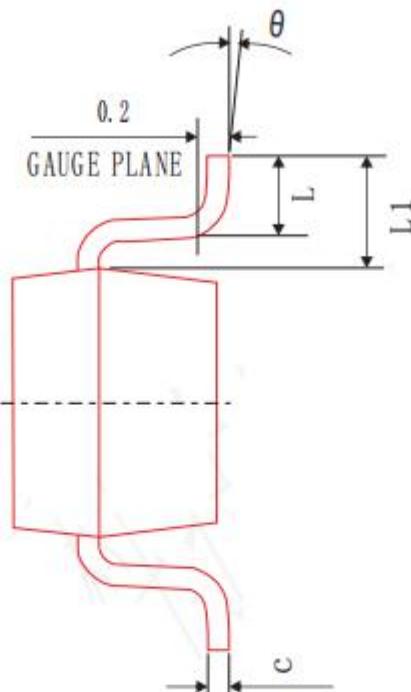
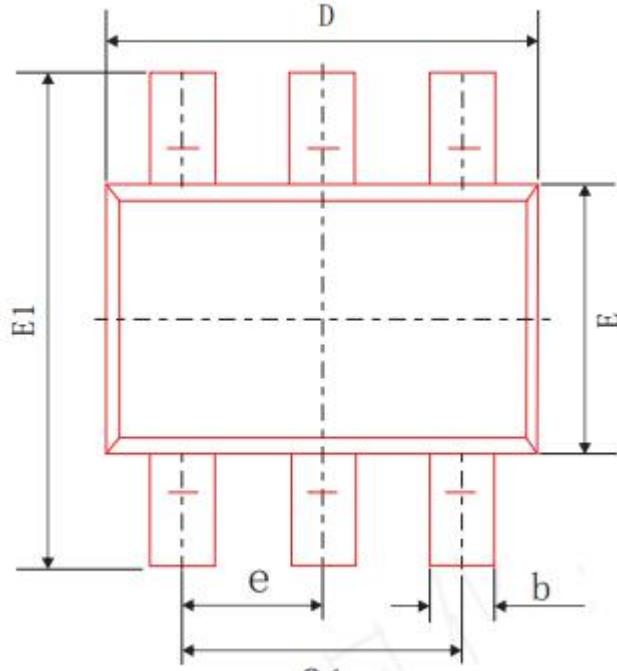


Figure 3. Unclamped Inductive Switching Test Circuit & Waveforms



Package Mechanical Data-SOT-363

COMMON DIMENSIONS
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	0.05	0.10
A2	0.90	0.95	1.00
b	0.20	0.25	0.30
c	0.08	0.10	0.15
e1	1.20	1.30	1.40
D	2.00	2.10	2.20
E	1.15	1.25	1.35
E1	2.15	2.30	2.45
L	0.26	0.36	0.46
θ	0°	4°	8°
L1		0.525 REF	
e		0.65 TYP	



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